

MPH 2 (MHP2-MHPU2)

High Power, High Current, Silver Ribbon Leded Capacitors

Features

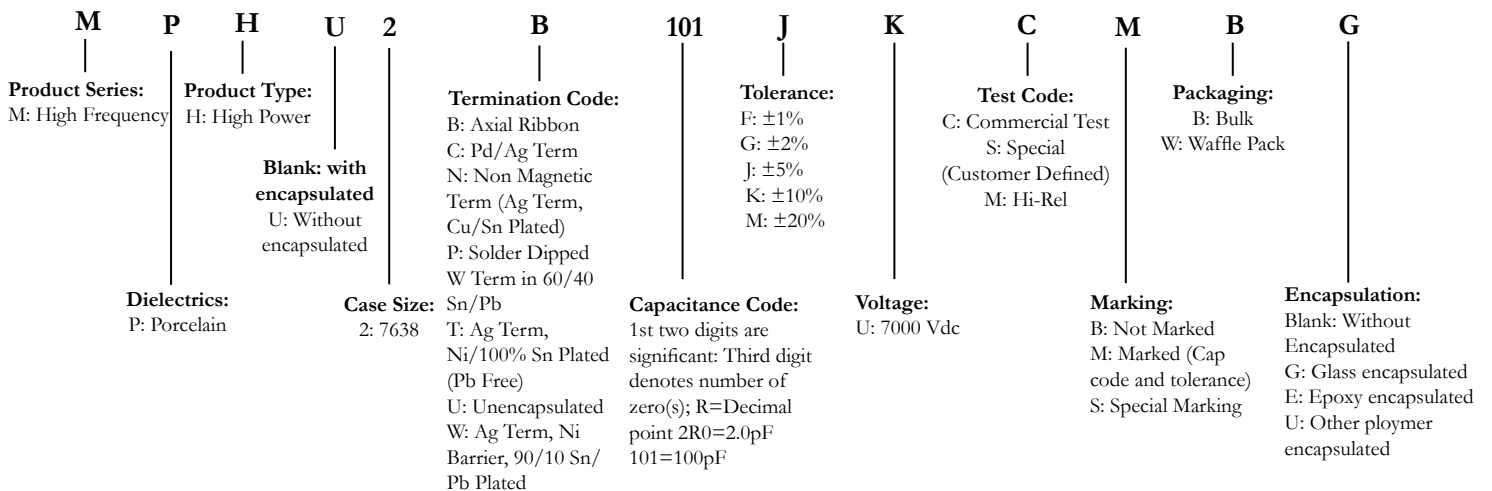
- Capacitance Range: 10pF to 75pF
- High Q Low ESR/ESL
- High RF Power
- Ultra Stable Performance
- Operating Voltages
 - DC Voltage: 7000Vdc
 - RF Voltage: 5000Vrms
- RF Current Rating: 12A rms
- Available with Encapsulation Option

Applications

- MRI Coils
- HF/RF Power Amplifiers
- Plasma Chambers
- Antenna Tuning
- High Power RF Transmitters
- Inductive Heating
- Semiconductor Equipment



AFM Part Number Code



Specification and Performance

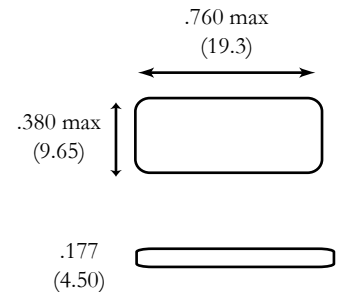
Piezoelectric and Aging Effect:	None
Temperature Range:	-55°C to +125°C
Temperature Coefficient of Capacitance:	+90±30ppm/°C
Quality Factor (Q) :	>10,000 (1pF~1000pF) at 1MHz; >10,000 (1100pF~5100pF) at 1KHz
Insulation Resistance (IR, Test Voltage 500V):	10 ⁵ MΩ min. at +25°C at rated WVDC; 10 ⁴ MΩ min. at +125°C at rated WVDC
Capacitance Drift:	±0.02% or ±0.02pF, whichever is greater

Standard Capacitance Values

CAP CODE	CAP (pF)	TOL	WVDC V	CAP CODE	CAP (pF)	TOL	WVDC V
100	10	F, G, J, K, M	7000	330	33	F, G, J, K, M	7000
110	11			360	36		
120	12			390	39		
130	13			430	43		
150	15			470	47		
160	16			510	51		
180	18			560	56		
200	20			620	62		
220	22			680	68		
240	24			750	75		
270	27						
300	30						

Chip Dimensions All Dimensions are in Inches (mm)

Dimensional Data	Length of Chip / Encapsulated (L) in (mm)	.760 (19.3)/ 1.062 (26.97) max after encapsulation
	Width of Chip/ Encapsulated (W) in (mm)	.380 (9.65)/.550 (13.97) max after encapsulation
	Thickness of Chip (T) in (mm) (Encapsulated) (max)	.177 (4.50) may increase to .236 (5.99) max. after glass encapsulation
	Ribbon Lead (Axial) in (mm)	Length: .750 (19.05) Width: .350 (8.89) Thickness: .010 (0.25)



Lead Options All Dimensions are in Inches (mm)

Construction Features	Ribbon Led	Lead Material	Pure Silver (99.9%)	Solder Plated Copper
		Lead Bonding	Silver Brazed	280°C Solder
		Encapsulation	Glass-Ceramic Coated on all 6 Sides	Glass-Ceramic Coated on all 4 Sides

